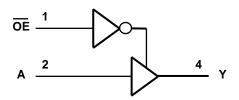


# **Pin Descriptions**

Pin Name	Description				
ŌE	Output Enable (active low)				
Α	Data Input				
GND	Ground				
Υ	Data Output				
Vcc	Supply Voltage				

# **Logic Diagram**



### **Function Table**

Inp	uts	Output			
ŌĒ	OE A				
L	Н	Н			
L	L	L			
Н	Х	Z			



### **Absolute Maximum Ratings (Note 3)**

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage applied to output in high impedance or I <sub>OFF</sub> state	-0.5 to 6.5	V
Vo	Voltage applied to output in high or low state	-0.3 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> <0	-50	mA
I <sub>ok</sub>	Output Clamp Current	-50	mA
Io	Continuous output current	±50	mA
	Continuous current through Vdd or GND	±100	mA
TJ	Operating Junction Temperature	-40 to 150	°C
T <sub>STG</sub>	Storage Temperature	-65 to 150	°C

Note: 3. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



# **Recommended Operating Conditions (Note 4)**

Symbol		Parameter	Min	Max	Unit	
\/	Operating Voltage	Operating	1.4	5.5	V	
V <sub>CC</sub>	Operating Voltage	Data retention only	1.2		V	
		V <sub>CC</sub> = 1.4 V to 1.95 V	0.65 X V <sub>CC</sub>			
V <sub>IH</sub>	High-level Input Voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
V IH		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0.7 X V <sub>CC</sub>			
		V <sub>CC</sub> = 1.4 V to 1.95 V		0.35 X V <sub>CC</sub>		
V <sub>IL</sub>	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
V <sub>IL</sub>	Low-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		0.8	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		0.3 X V <sub>CC</sub>		
V <sub>I</sub>	Input Voltage		0	5.5	V	
Vo	Output Voltage		0	V <sub>CC</sub>	V	
		Vcc=1.4 V		-3		
	I Cala I and a dank a mark	V <sub>CC</sub> = 1.65 V		-4	A	
		V <sub>CC</sub> = 2.3 V		-8		
I <sub>OH</sub>	High-level output current	V 2V		-16	mA	
		$V_{CC} = 3 V$		-24		
		V <sub>CC</sub> = 4.5 V		-32		
		Vcc=1.4 V		3		
		V <sub>CC</sub> = 1.65 V		4		
	Lavelaval avitavit avimost	V <sub>CC</sub> = 2.3 V		8	mA	
I <sub>OL</sub>	Low-level output current	V 2V		16		
		$V_{CC} = 3 V$		24		
		V <sub>CC</sub> = 4.5 V		32		
		V <sub>CC</sub> = 1.4 to 3V		20		
Δt/ΔV	Input transition rise or fall	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V	
	rate	$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		5		
T <sub>A</sub>	Operating free-air temperature		-40	85	°C	

Note: 4. Unused inputs should be held at Vcc or Ground.



# Electrical Characteristics (All typical values are at Vcc = 3.3V, T<sub>A</sub> = 25°C)

Over recommended free-air temperature range (unless otherwise noted)

Symbol	Parameter	Test Conditions	Vcc	Min	Тур.	Max	Unit	
		I <sub>OH</sub> = -100μA	1.4 V to 5.5V	V <sub>CC</sub> - 0.1				
		$I_{OH} = -3mA$	1.4 V	1.05				
		$I_{OH} = -4mA$	1.65 V	1.2				
V <sub>OH</sub>	High Level Output Voltage	$I_{OH} = -8mA$	2.3V	1.9			V	
	Voltage	I <sub>OH</sub> = -16mA	3 V	2.4				
		I <sub>OH</sub> = -24mA	3 V	2.3				
		I <sub>OH</sub> = -32mA	4.5 V	3.8				
		$I_{OL} = 100 \mu A$	1.4 V to 5.5V			0.1		
		$I_{OL} = 3mA$	1.4V			.4		
		I <sub>OL</sub> = 4mA	1.65 V			0.45		
$V_{OL}$	High-level Input Voltage	$I_{OL} = 8mA$	2.3V			0.3	V	
		I <sub>OL</sub> = 16mA	3 V			0.4		
		I <sub>OL</sub> = 24mA	3 V			0.55		
		$I_{OL} = 32mA$	4.5			0.55		
I	Input Current	$V_1 = 5.5 \text{ V or GND}$	0 to 5.5 V			± 5	μA	
I <sub>OFF</sub>	Power Down Leakage Current	$V_1$ or $V_0 = 5.5V$	0			± 10	μA	
l <sub>OZ</sub>	Z State Leakage Current	V <sub>O</sub> =0 to 5.5V	3.6V			10	μA	
I <sub>CC</sub>	Supply Current	$V_1 = 5.5V$ of GND $I_0=0$	1.4 V to 5.5V			10	μA	
ΔI <sub>CC</sub>	Additional Supply Current	One input at V <sub>CC</sub> – 0.6 V Other inputs at V <sub>CC</sub> or GND	3 V to 5.5V			500	μΑ	
Ci	Input Capacitance	$V_i = V_{CC} - or GND$	3.3		3.5		pF	
	The man of Decistors	SOT25	(Note 5)		204			
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	SOT353	(Note 5)		371		°C/W	
	CONTROL AND CHE	DFN1410	(Note 5)		430			
	The second Description	SOT25	(Note 5)		52			
$\theta_{JC}$	Thermal Resistance Junction-to-Case	SOT353	(Note 5)		143		°C/W	
	Junction-to-Case	DFN1410	(Note 5)		190			

Note: 5. Test condition for SOT25, SOT353 and DFN1410: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



### **Switching Characteristics**

Over recommended free-air temperature range, CL = 15pF (see Figure 1)

Parameter From	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V ).2V		3.3 V 3.3V	Vcc :	= 5 V ).5V	Unit	
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>pd</sub>	Α	Υ	1.9	6.9	1.3	4.8	0.5	3.6	0.4	3	0.4	3	ns

Over recommended free-air temperature range, CL = 30 or 50pF as noted (see Figure 2)

Parameter	From			_	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V ).2V		: 3.3 V ).3V		= 5 V ).5V	Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max				
t <sub>pd</sub>	Α	Y	2.8	9	1.9	6.3	0.9	4.4	0.8	3.6	0.9	3.6	ns			
t <sub>en</sub>	OE	Υ	3.3	10.1	2.3	7	1.2	5.2	0.8	4.3	0.9	4.5				
t <sub>dis</sub>	OE	Y	1.3	9.2	0.9	6.4	0.8	4	0.8	4.1	0.9	3.7				

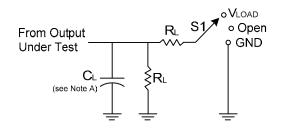
### **Operating Characteristics**

 $T_A = 25$  °C

	Parameter			Vcc = 1.5 V	Vcc = 1.8 V	Vcc = 2.5 V	Vcc = 3.3 V	Vcc = 5 V	Unit
			Conditions	TYP	TYP	TYP	TYP	TYP	
	Power dissipation	Outputs enabled	f = 10 MHz	20	20	20	21	22	٠,٢
C <sub>pd</sub>	capacitance	Outputs disabled	I = IU WIMZ	2	2	2	2	4	pF

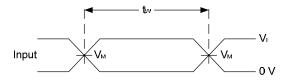


#### **Parameter Measurement Information**

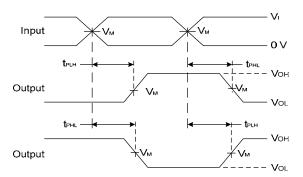


TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
$t_{PLZ}/t_{PZL}$	Vload
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

Vcc	In	puts	V		Б
VCC	Vı	t <sub>r</sub> /t <sub>f</sub>	· V <sub>M</sub>	CL	RL
1.5V±0.1V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	15pF	1ΜΩ
1.8V±0.15V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	15pF	1ΜΩ
2.5V±0.2V	$V_{CC}$	≤2ns	V <sub>CC</sub> /2	15pF	1ΜΩ
3.3V±0.3V	3V	≤2.5ns	1.5V	15pF	1ΜΩ
5V±0.5V	V <sub>CC</sub>	≤2.5ns	V <sub>CC</sub> /2	15pF	1ΜΩ



#### **Voltage Waveform Pulse Duration**



**Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs** 

Output Vм Control Output Waveform 1 S1 at VLOAD (see Note B) Output Waveform 2 Von - Va S1 at GND (see Note B) **~** 0∨

**Voltage Waveform Enable and Disable Times** Low and High Level Enabling

Notes: A. Includes test lead and test apparatus capacitance.

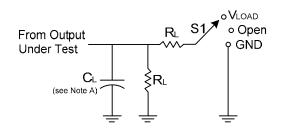
- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
- C. Inputs are measured separately one transition per measurement.
- D. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis.</sub>
- E.  $t_{\text{PZL}}$  and  $t_{\text{PZH}}$  are the same as  $t_{\text{EN}}$
- F. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>PD.</sub>

Figure 1. Load Circuit and Voltage Waveforms

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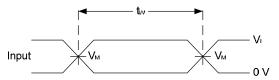


### **Parameter Measurement Information (Continued)**

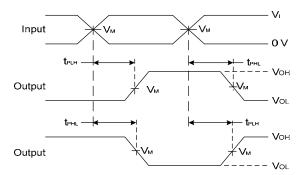


TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
$t_{PLZ}/t_{PZL}$	Vload
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

Vcc	Inj	outs	V <sub>M</sub>	CL	RL
	Vi	t <sub>r</sub> /t <sub>f</sub>	- IVI	OL.	
1.5V±0.1V	V <sub>cc</sub>	≤2ns	V <sub>CC</sub> /2	30pF	1ΚΩ
1.8V±0.15V	V <sub>cc</sub>	≤2ns	V <sub>CC</sub> /2	30pF	1ΚΩ
2.5V±0.2V	V <sub>cc</sub>	≤2ns	V <sub>CC</sub> /2	30pF	500Ω
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω
5V±0.5V	V <sub>CC</sub>	≤2.5ns	V <sub>CC</sub> /2	50pF	500Ω



#### **Voltage Waveform Pulse Duration**



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Output
Control

Output
Waveform 1
S1 at V<sub>LOAD</sub>
(see Note B)

Output
Waveform 2
S1 at GND
(see Note B)

V<sub>M</sub>

Voltage Waveform Enable and Disable Times
Low and High Level Enabling

Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
- C. Inputs are measured separately one transition per measurement.
- D.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis.}$
- E.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{EN0}$
- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD.}$

Figure 2. Load Circuit and Voltage Waveforms



### **Ordering Information**

74LVCE1G 125 XXX -Logic Device **Function** Package Packing 74: Logic Prefix 125: 3-State Buffer W5: SOT25 7: Tape & Reel

LVCE: 1.4 to 5.5V

Family

1G: One gate

**SE: SOT353** 

FZ4: DFN1410

Device	Package Packaging		7" Tape and Reel	
Device	Code	(Note 5)	Quantity	Part Number Suffix
74LVCE1G125W5-7	W6	SOT25	3000/Tape & Reel	-7
74LVCE1G125SE-7	SE	SOT353	3000/Tape & Reel	-7
74LVCE1G125FZ4-7	FZ4	DFN1410	5000/Tape & Reel	-7

Note: 6. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

OE-Low



### **Marking Information**

#### (1) SOT25 and SOT353

### (Top View)

5 4 XX Y WX

2

3

XX: Identification code

Y: Year 0~9

W : Week : A~Z : 1~26 week;

a~z: 27~52 week; z represents 52 and 53 week

X: A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G125W5	SOT25	PY
74LVCE1G125SE	SOT353	PY

#### (2) DFN1410

### (Top View)

<u>XX</u>  XX: Identification Code

Y: Year: 0~9

 $\underline{\overline{W}}$ : Week : A~Z : 1~26 week;

a~z: 27~52 week; z represents 52 and 53 week

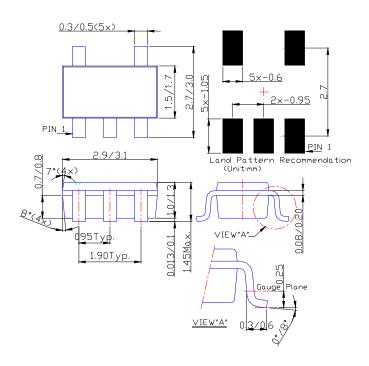
 $\underline{X}$ : A~Z: Internal code

Part Number	Package	Identification Code
74LVCF1G125F74	DFN1410	PY

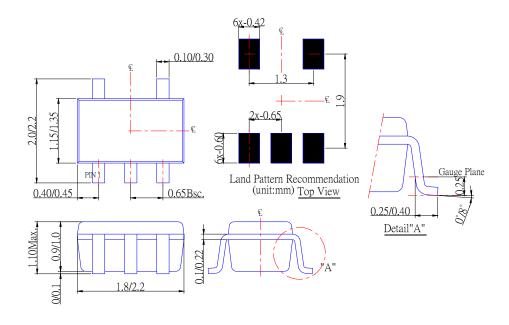


# Package Outline Dimensions (All Dimensions in mm)

### (1) Package Type: SOT25



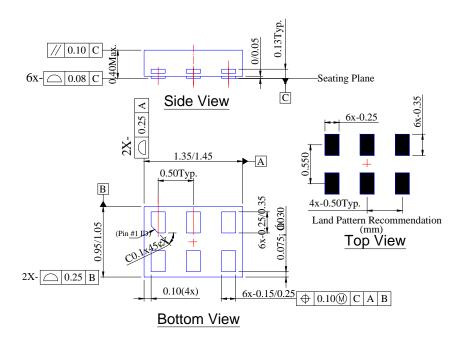
### (2) Package Type: SOT353





### Package Outline Dimensions (All Dimensions in mm)

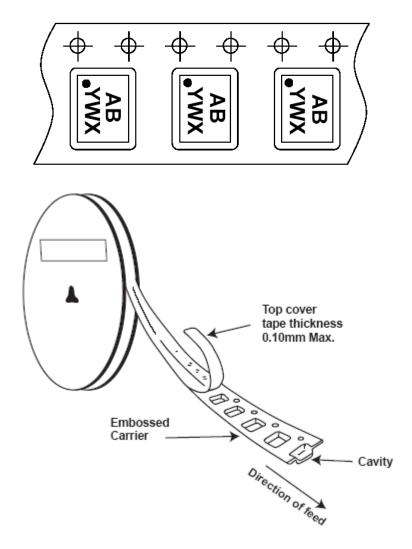
### (3) Package Type: DFN1410





## **Taping Orientation (Note 7)**

#### For DFN1410



Note: 7. The taping orientation of the other package type can be found on our website at http://www.diodes.com/datasheets/ap02007.pdf



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